

Date	User	Film	Recipe	Dep.time (sec)	Thickness (Å)	JAW EC-400 (Woolam S. E.)			Avg Index	Index+1%	Index -1%	Avg.dep. rate				HF e.r.	Stress (MPa)	Avg. Stress (MPa)	Avg+10% (MPa)	Avg-10% (MPa)	LPD (light point defects)		Comment	Mike Silva
						Index @ 632.8nm	Index @ 1550nm	Index @ 632.8nm				(nm/min)	(nm/min)	(nm/min)	(nm/min)						LPD before deposition	LPD after deposition		
Nitride																								
01/09/14	Bilja	SIN	iN_dep	900	617.69	1.962	1.955	1.967	2.026	1.908	4.12	4.10	4.51	3.69	14.53	-1721.22	-1614.84	-1776.33	-1453.36	80	15039	Failed, 1st run		
01/09/14	Bilja	SIN	iN_dep	900	592.91	1.962	1.969	1.967	2.026	1.908	3.95	4.10	4.51	3.69			-1614.84	-1776.33	-1453.36	68	4755	Particles mostly in the center of wafer, 2nd run		
01/31/14	Bilja	SIN	iN_dep	900	585.66	1.948	1.945	1.967	2.026	1.908	3.90	4.10	4.51	3.69	26.48	-1552.92	-1614.84	-1776.33	-1453.36					
03/19/14	Bilja	SIN	iN_dep	900	662.23	1.996	1.979	1.967	2.026	1.908	4.41	4.10	4.51	3.69	to do!	-1570.39	-1614.84	-1776.33	-1453.36	89	662			

Thickness	614.62	Avg. Index	1.967	Avg. Dep. Rate	4.10	Avg HF e.r.	
		Avg+3%	2.026	Avg+10%	4.51	Avg Stress	-1614.84
		Avg-3%	1.908	Avg-10%	3.69	Avg+10%	-1776.33
						Avg-10%	-1453.36

